

Item	Project		Capability	Note
1	Layer Count		1L ~ 40L HDI,Anylayer,depth controlled slot,Probe Card	
2	Laminate Materials		FR4,PTFE,Polymide,Rogers,MCPCB,FR4+Rogers, Isola+FR4	
3	Board Thickness	Double-sided	0.2mm-8.0mm	
		Multilayer	0.3mm-8.0mm	
4	Size	finished dimensions(Maxma)	700mm	width<500mm
		finished dimensions(Minima)	10mm	
5	Inner Layers	Minimum space from drilling to inner pattern□	3.5mil	
		Minima core thickness	0.08mm	
		Pad Ring(Minima)	4mil	Tenting
		Minimum trace width / space	2.5/2.5mil	Copper Weight 0.5oz or less
6	Drilling	Minimum size□	0.1mm	
		hole tolerance (PTH & NPTH)	NPTH+/- 2mil PTH+/- 3mil	
		Drill Deviation (True position size)	+/- 2mil	
		Laser Drill	0.3mm or less	
		Aspect ratio□	20	
7	SMD PAD	PAD Deviation	±25um	
		Pad Size (minima)	100um	
		Pad Size tolerance	±30um	
		Pad Pitch	200um	
		Pad Spacing	100um	
8	Outer Layers	Minimum trace width / space	2.5/2.5mil	Copper Weight 0.5oz or less
9	Surface Finish□	HASL / Lead Free HASL(thickness)	0.7mil	
		immersion gold(thickness)	1u"-8u"	
		Hard gold plating (thickness)	3u" ~ 50u"	
10	Solder Mask□	Thickness	0.4 mil ~ 2mil	
		Deviation	2mil	
		color	green,light green,matte green,white,extreme white,black,matte black,purple,dark brown,yellow,red,blue,transparent	
11	Silkscreen□	color	white,black,yellow,red,blue,green	
		Minimum size□	28mil	
		Minimum trace width□	3mil	inkjet printing
14	Copper Weight	Inner copper weight□	1/3 oz ~ 6 oz	
		Outer copper weight□	0.7oz ~ 10oz	
15	Bow and twist□		3/1000~7/1000	
16	BGA PAD	Ball Pitch	12mil	no trace between BGA
		Ball spacing	4mil	